EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1038	"438"/$.ccls. and (die ic chip) with (thin$4 grind$3 polish$3) and (substrate board carrier interposer) with (thin$4 grind$3 polish$3) and first adj3 (support substrate board carrier interposer) and second adj3 (support substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 20:15
L2	181	"29"/$.ccls. and (die ic chip) with (thin$4 grind$3 polish$3) and (substrate board carrier interposer) with (thin$4 grind$3 polish$3) and first adj3 (support substrate board carrier interposer) and second adj3 (support substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 20:22
L3	2058	"257"/$.ccls. and (die ic chip) with (thin$4 grind$3 polish$3) and (substrate board carrier interposer) with (thin$4 grind$3 polish$3) and first adj3 (support substrate board carrier interposer) and second adj3 (support substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 20:24